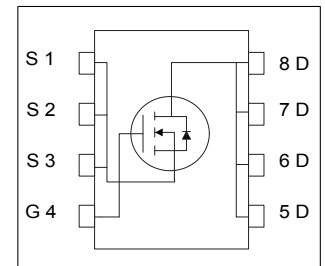


# MOSFET

## OptiMOS™ Power-MOSFET, 30 V

### Features

- Optimized SyncFET for high performance buck converter
- Integrated monolithic Schottky-like diode
- Very low on-resistance  $R_{DS(on)}$  @  $V_{GS}=4.5$  V
- 100% avalanche tested
- Superior thermal resistance
- N-channel
- Qualified according to JEDEC<sup>1)</sup> for target applications
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21



**Table 1 Key Performance Parameters**

Parameter	Value	Unit
$V_{DS}$	30	V
$R_{DS(on),max}$	3.7	m $\Omega$
$I_D$	78	A
$Q_{OSS}$	12	nC
$Q_G(0V..10V)$	17	nC

Type / Ordering Code	Package	Marking	Related Links
BSC0904NSI	PG-TDSON-8	0904NSI	-

<sup>1)</sup> J-STD20 and JESD22

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## 1 Maximum ratings

at  $T_j=25\text{ °C}$ , unless otherwise specified

**Table 2 Maximum ratings**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current	$I_D$	-	-	78	A	$V_{GS}=10\text{ V}$ , $T_C=25\text{ °C}$ $V_{GS}=10\text{ V}$ , $T_C=100\text{ °C}$ $V_{GS}=4.5\text{ V}$ , $T_C=25\text{ °C}$ $V_{GS}=4.5\text{ V}$ , $T_C=100\text{ °C}$ $V_{GS}=10\text{ V}$ , $T_A=25\text{ °C}$ , $R_{thJA}=50\text{ K/W}^1)$
		-	-	49		
		-	-	66		
		-	-	41		
		-	-	20		
Pulsed drain current <sup>2)</sup>	$I_{D,pulse}$	-	-	312	A	$T_C=25\text{ °C}$
Avalanche current, single pulse <sup>3)</sup>	$I_{AS}$	-	-	30	A	$T_C=25\text{ °C}$
Avalanche energy, single pulse	$E_{AS}$	-	-	14	mJ	$I_D=30\text{ A}$ , $R_{GS}=25\text{ }\Omega$
Gate source voltage	$V_{GS}$	-20	-	20	V	-
Power dissipation	$P_{tot}$	-	-	37	W	$T_C=25\text{ °C}$ $T_A=25\text{ °C}$ , $R_{thJA}=50\text{ K/W}^1)$
		-	-	2.5		
Operating and storage temperature	$T_j$ , $T_{stg}$	-55	-	150	°C	IEC climatic category; DIN IEC 68-1: 55/150/56

## 2 Thermal characteristics

**Table 3 Thermal characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case, bottom	$R_{thJC}$	-	-	3.4	K/W	-
Thermal resistance, junction - case, top	$R_{thJC}$	-	-	20	K/W	-
Device on PCB, 6 cm <sup>2</sup> cooling area <sup>1)</sup>	$R_{thJA}$	-	-	50	K/W	-

<sup>1)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

<sup>2)</sup> See figure 3 for more detailed information

<sup>3)</sup> See figure 13 for more detailed information

### 3 Electrical characteristics

at  $T_j=25\text{ °C}$ , unless otherwise specified

**Table 4 Static characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	30	-	-	V	$V_{GS}=0\text{ V}$ , $I_D=10\text{ mA}$
Breakdown voltage temperature coefficient	$dV_{(BR)DSS}/dT_j$	-	15	-	mV/K	$I_D=10\text{ mA}$ , referenced to $25\text{ °C}$
Gate threshold voltage	$V_{GS(th)}$	1.2	-	2	V	$V_{DS}=V_{GS}$ , $I_D=250\text{ }\mu\text{A}$
Zero gate voltage drain current	$I_{DSS}$	-	-	0.5	mA	$V_{DS}=24\text{ V}$ , $V_{GS}=0\text{ V}$ $V_{DS}=24\text{ V}$ , $V_{GS}=0\text{ V}$ , $T_j=125\text{ °C}$
Gate-source leakage current	$I_{GSS}$	-	10	100	nA	$V_{GS}=20\text{ V}$ , $V_{DS}=0\text{ V}$
Drain-source on-state resistance	$R_{DS(on)}$	-	4.2	5.2	m $\Omega$	$V_{GS}=4.5\text{ V}$ , $I_D=30\text{ A}$ $V_{GS}=10\text{ V}$ , $I_D=30\text{ A}$
Gate resistance	$R_G$	0.5	0.9	1.8	$\Omega$	-
Transconductance	$g_{fs}$	43	86	-	S	$ V_{DS} >2 I_D R_{DS(on)max}$ , $I_D=30\text{ A}$

**Table 5 Dynamic characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	$C_{iss}$	-	1100	1500	pF	$V_{GS}=0\text{ V}$ , $V_{DS}=15\text{ V}$ , $f=1\text{ MHz}$
Output capacitance	$C_{oss}$	-	460	610	pF	$V_{GS}=0\text{ V}$ , $V_{DS}=15\text{ V}$ , $f=1\text{ MHz}$
Reverse transfer capacitance	$C_{rss}$	-	64	-	pF	$V_{GS}=0\text{ V}$ , $V_{DS}=15\text{ V}$ , $f=1\text{ MHz}$
Turn-on delay time	$t_{d(on)}$	-	3.3	-	ns	$V_{DD}=15\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=30\text{ A}$ , $R_G=1.6\text{ }\Omega$
Rise time	$t_r$	-	4.4	-	ns	$V_{DD}=15\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=30\text{ A}$ , $R_G=1.6\text{ }\Omega$
Turn-off delay time	$t_{d(off)}$	-	16	-	ns	$V_{DD}=15\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=30\text{ A}$ , $R_G=1.6\text{ }\Omega$
Fall time	$t_f$	-	3.0	-	ns	$V_{DD}=15\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=30\text{ A}$ , $R_G=1.6\text{ }\Omega$

**Table 6 Gate charge characteristics<sup>1)</sup>**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	$Q_{GS}$	-	2.9	3.8	nC	$V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }4.5\text{ V}$
Gate charge at threshold	$Q_{g(th)}$	-	1.7	2.3	nC	$V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }4.5\text{ V}$
Gate to drain charge	$Q_{gd}$	-	2.9	3.8	nC	$V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }4.5\text{ V}$
Switching charge	$Q_{sw}$	-	4.1	5.4	nC	$V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }4.5\text{ V}$
Gate charge total	$Q_g$	-	8.5	11.3	nC	$V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }4.5\text{ V}$
Gate plateau voltage	$V_{plateau}$	-	2.7	-	V	$V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }4.5\text{ V}$
Gate charge total	$Q_g$	-	17	22	nC	$V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$
Gate charge total, sync. FET	$Q_{g(sync)}$	-	6.8	9.0	nC	$V_{DS}=0.1\text{ V}$ , $V_{GS}=0\text{ to }4.5\text{ V}$
Output charge	$Q_{oss}$	-	12	16.5	nC	$V_{DD}=15\text{ V}$ , $V_{GS}=0\text{ V}$

<sup>1)</sup> See "Gate charge waveforms" for parameter definition

**Table 7 Reverse diode**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode continuous forward current	$I_S$	-	-	37	A	$T_C=25\text{ °C}$
Diode pulse current	$I_{S,pulse}$	-	-	148	A	$T_C=25\text{ °C}$
Diode forward voltage	$V_{SD}$	-	0.56	0.7	V	$V_{GS}=0\text{ V}, I_F=3\text{ A}, T_j=25\text{ °C}$
Reverse recovery charge	$Q_{rr}$	-	2	-	nC	$V_R=15\text{ V}, I_F=I_S, di_F/dt=400\text{ A}/\mu\text{s}$

### 4 Electrical characteristics diagrams

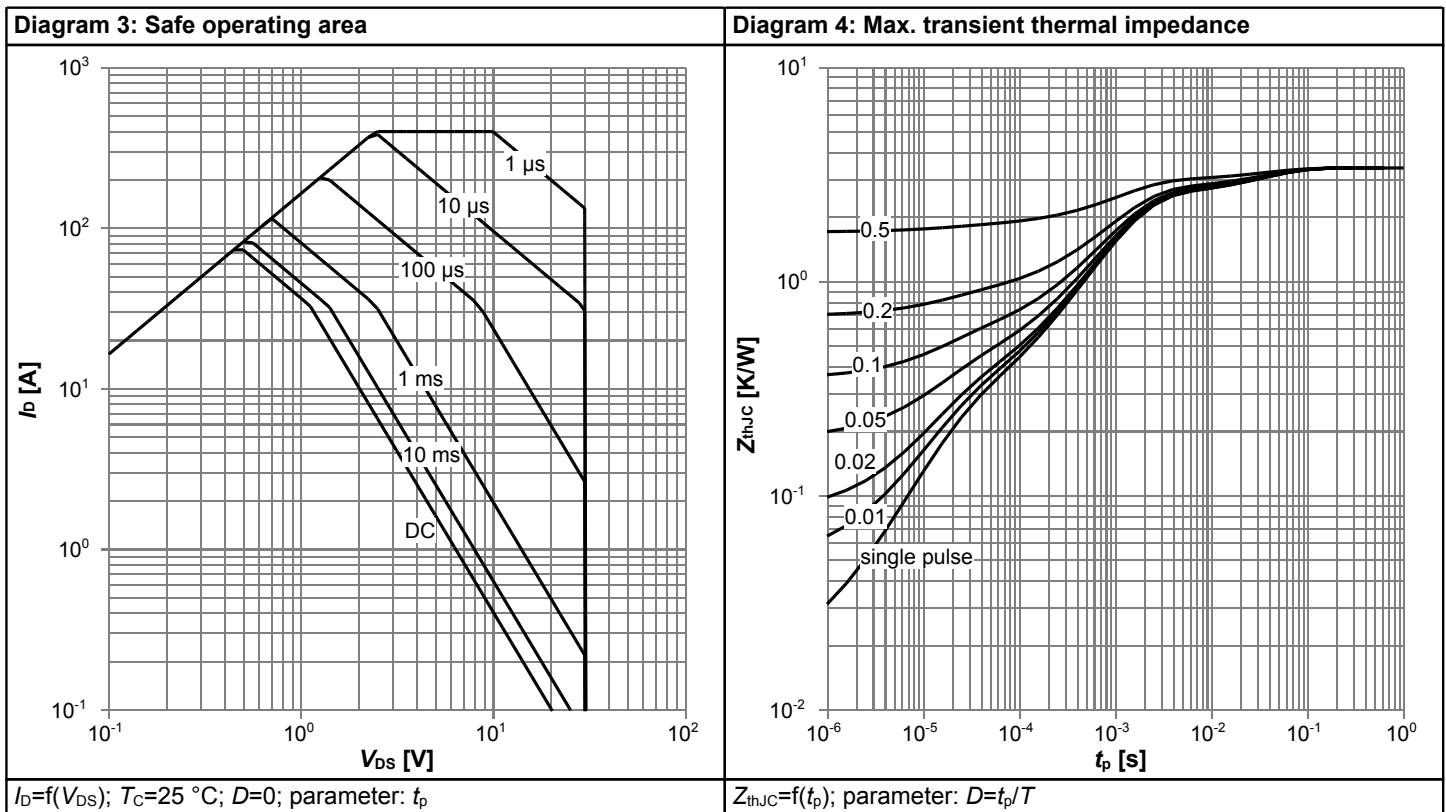
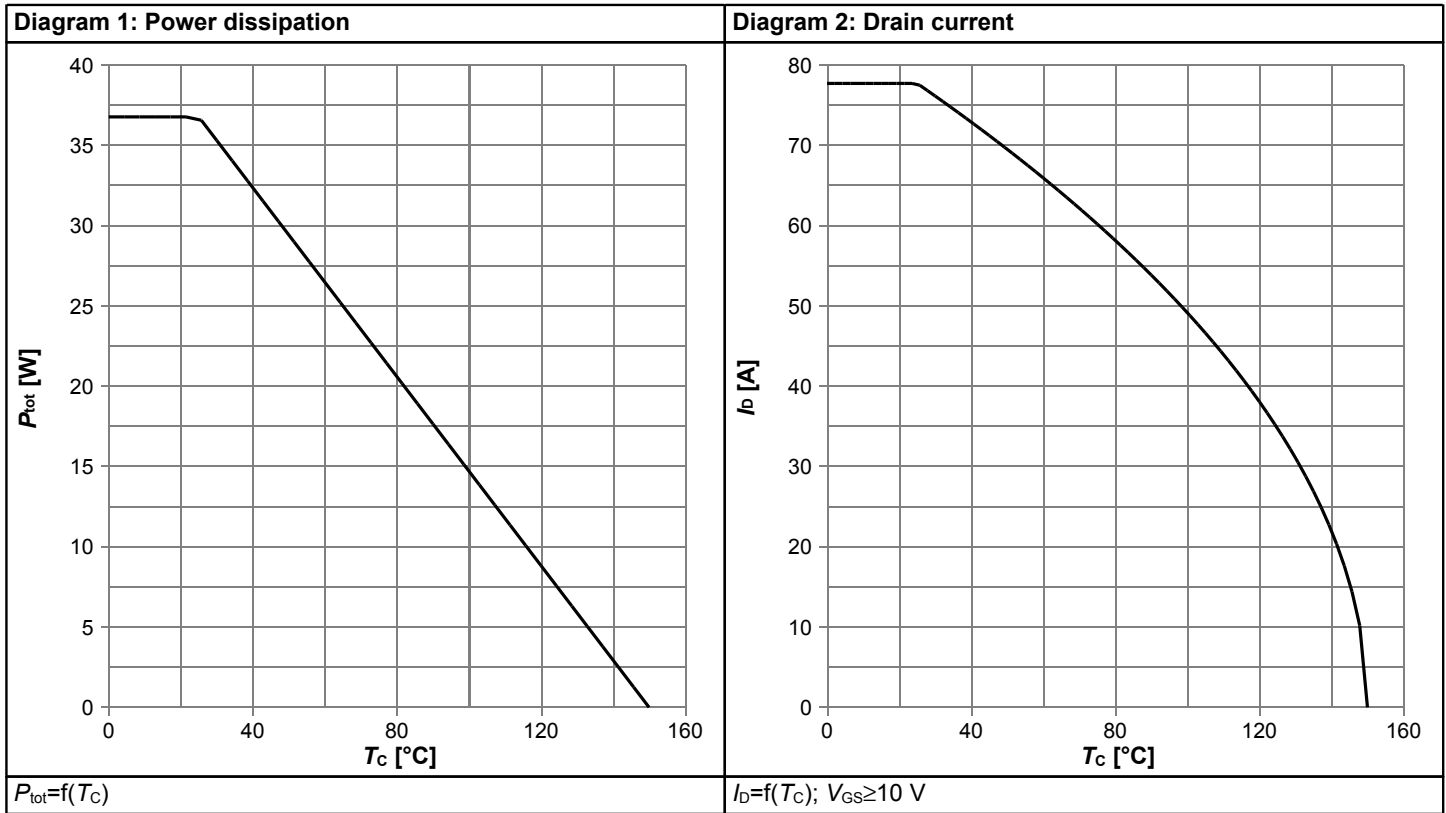
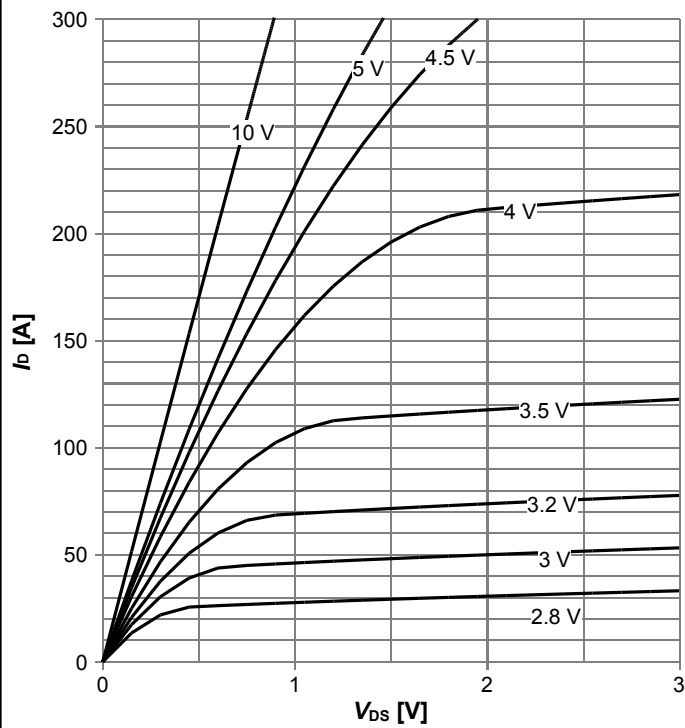
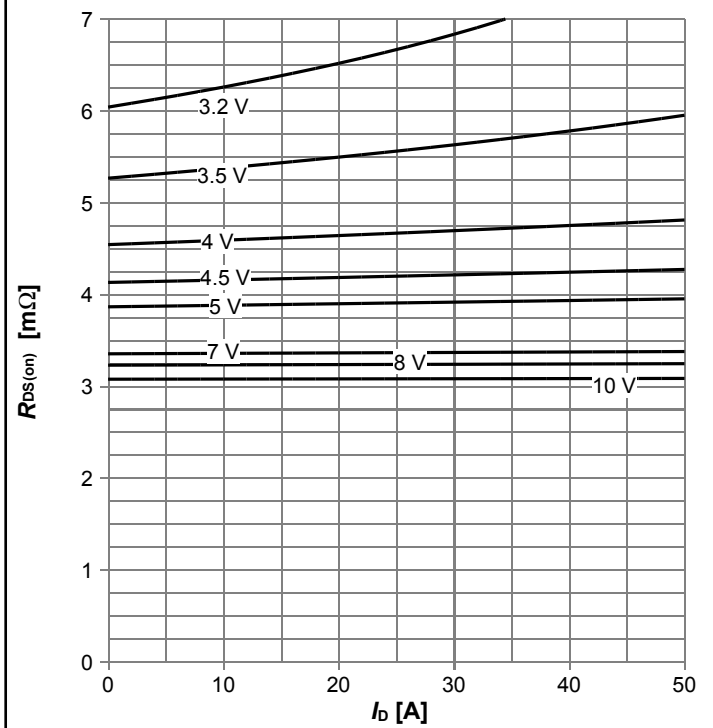


Diagram 5: Typ. output characteristics



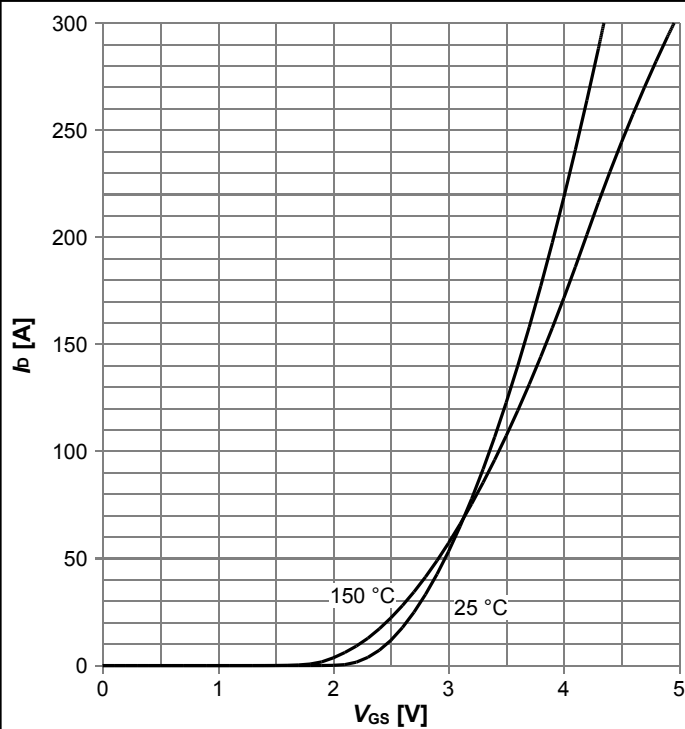
$I_D = f(V_{DS}); T_j = 25\text{ °C};$  parameter:  $V_{GS}$

Diagram 6: Typ. drain-source on resistance



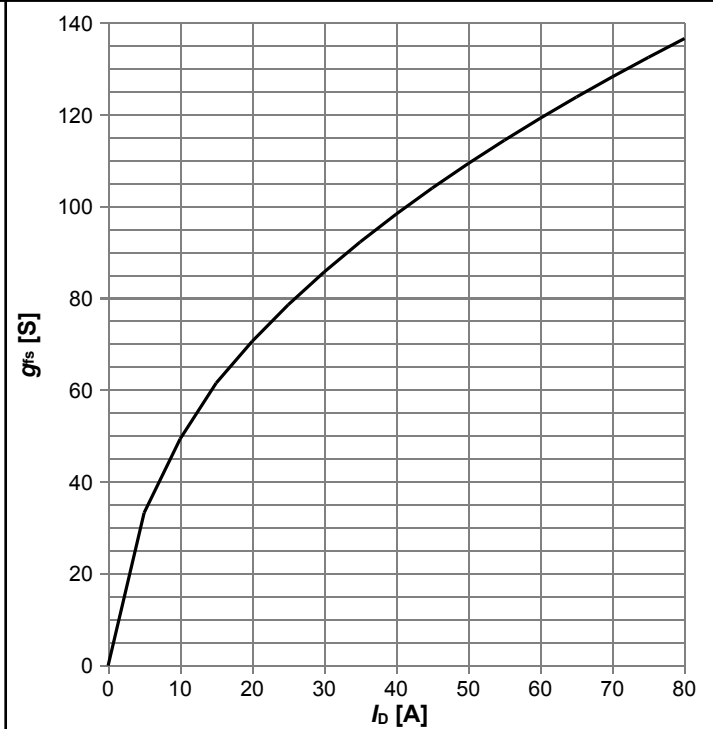
$R_{DS(on)} = f(I_D); T_j = 25\text{ °C};$  parameter:  $V_{GS}$

Diagram 7: Typ. transfer characteristics



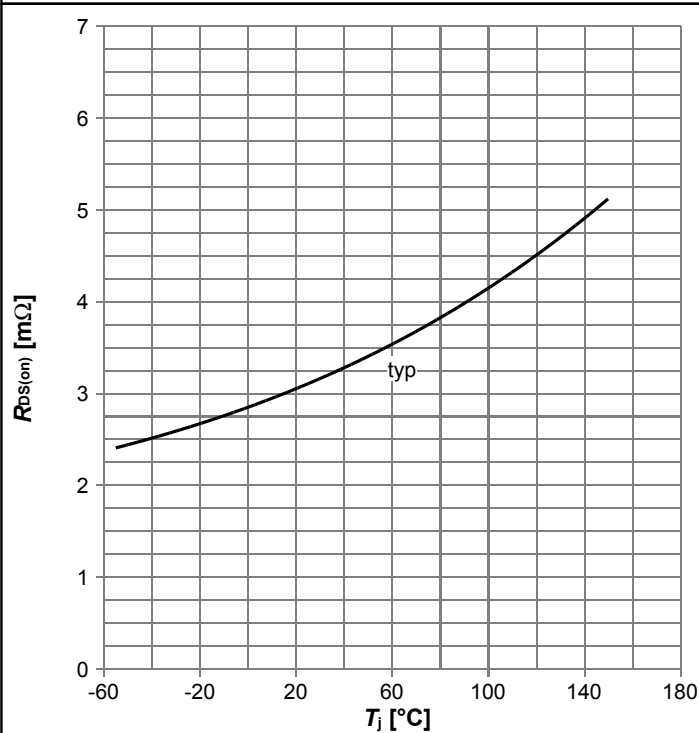
$I_D = f(V_{GS}); |V_{DS}| > 2|I_D|R_{DS(on)max};$  parameter:  $T_j$

Diagram 8: Typ. forward transconductance



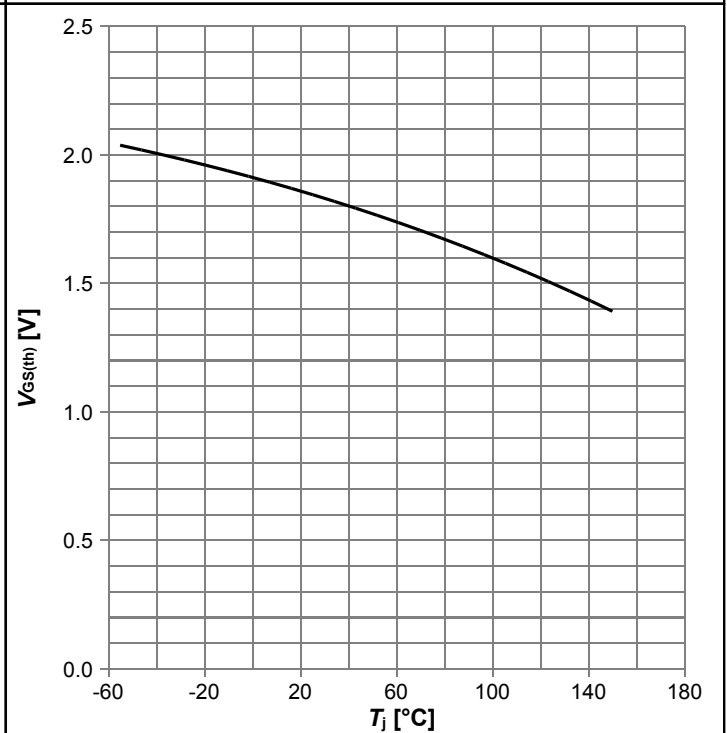
$g_{fs} = f(I_D); T_j = 25\text{ °C}$

Diagram 9: Drain-source on-state resistance



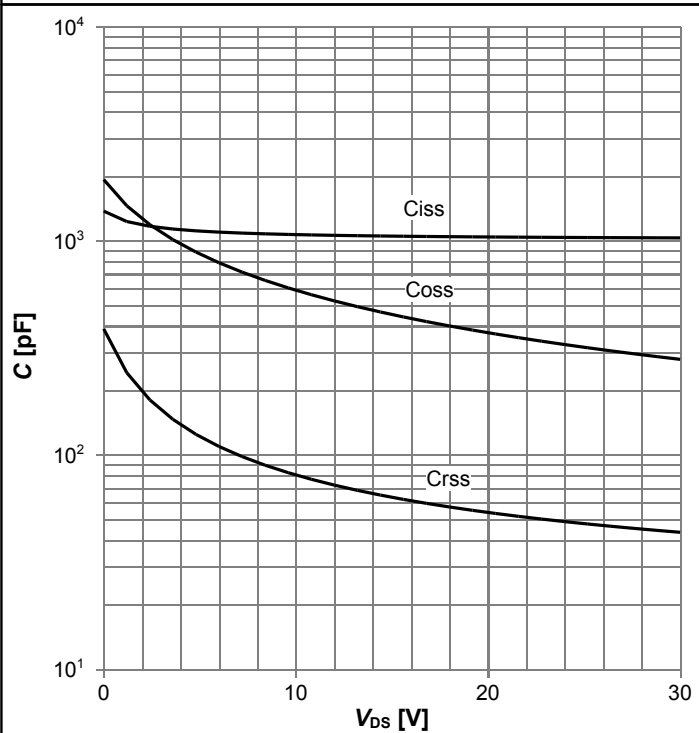
$R_{DS(on)}=f(T_j)$ ;  $I_D=30$  A;  $V_{GS}=10$  V

Diagram 10: Typ. gate threshold voltage



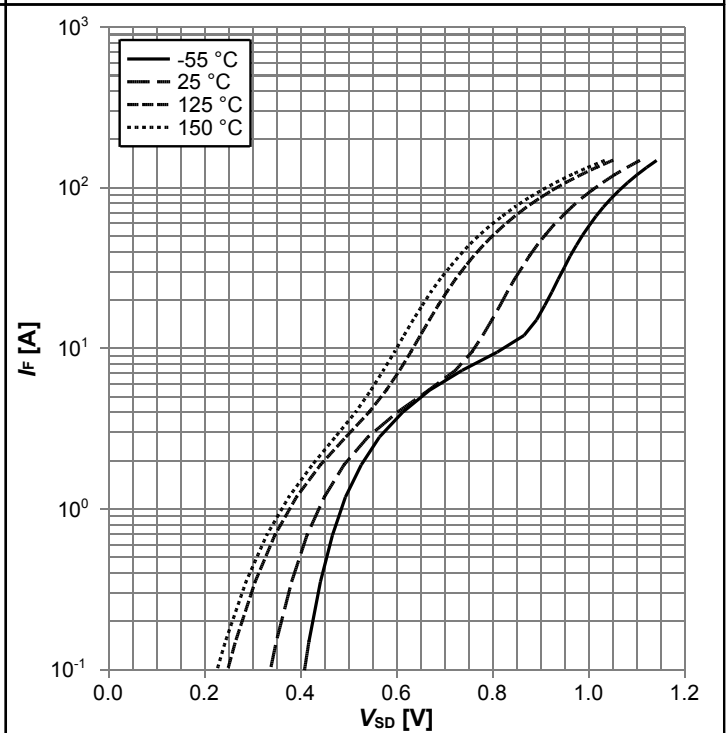
$V_{GS(th)}=f(T_j)$ ;  $V_{GS}=V_{DS}$ ;  $I_D=10$  mA

Diagram 11: Typ. capacitances



$C=f(V_{DS})$ ;  $V_{GS}=0$  V;  $f=1$  MHz

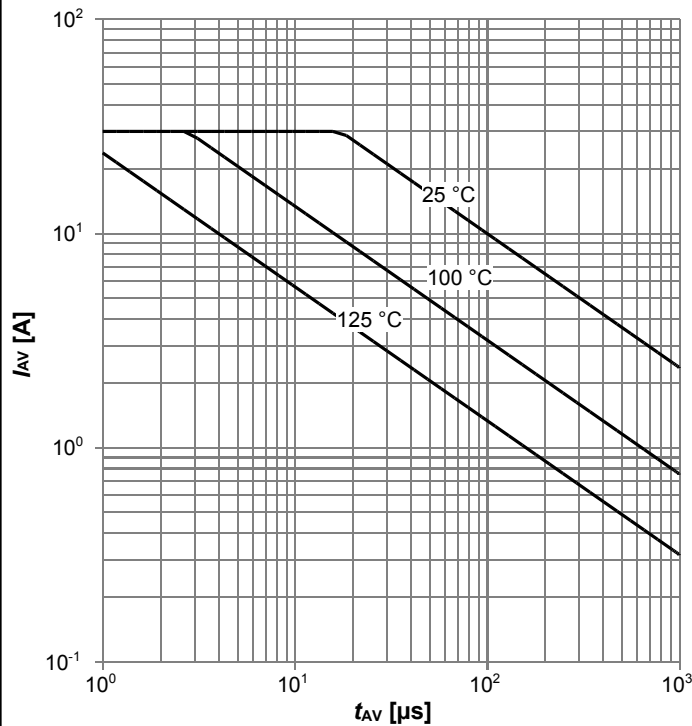
Diagram 12: Forward characteristics of reverse diode



$I_F=f(V_{SD})$ ; parameter:  $T_j$

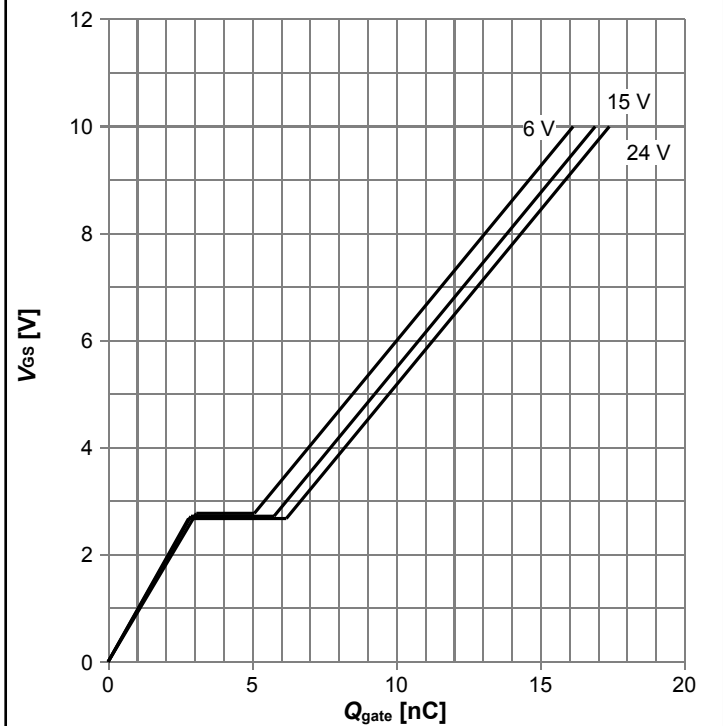


Diagram 13: Avalanche characteristics



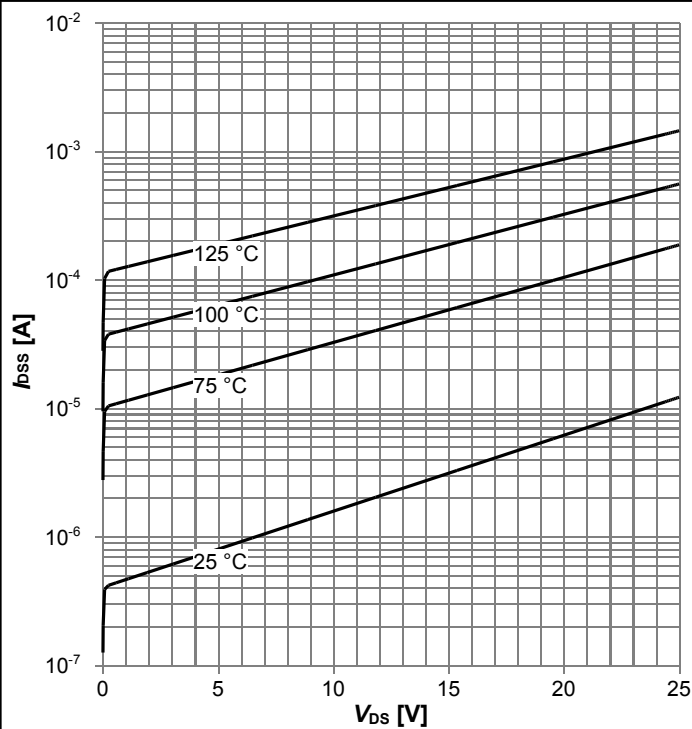
$I_{AS}=f(t_{AV}); R_{GS}=25 \Omega$ ; parameter:  $T_{j(start)}$

Diagram 14: Typ. gate charge



$V_{GS}=f(Q_{gate}); I_D=30$  A pulsed; parameter:  $V_{DD}$

Diagram 15: Typ. drain-source leakage current



$I_{BSS}=f(V_{DS}); V_{GS}=0$  V; parameter:  $T_j$

Diagram Gate charge waveforms



## 5 Package Outlines

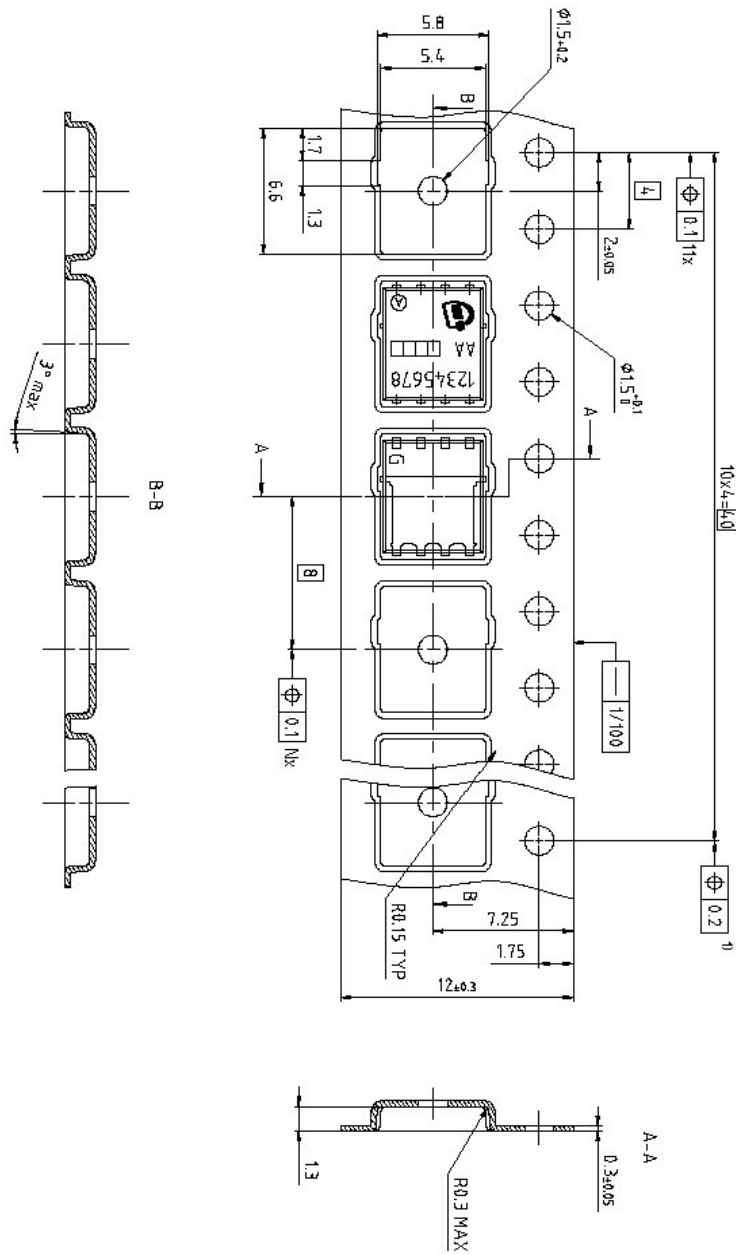


- 1) EXCLUDING MOLD FLASH
- 2) REMOVAL ON MOLD GATE  
INTRUSION 0.1 MM  
PROTRUSION 0.1 MM  
LEAD LENGTH UP TO ANTI FLASH LINE  
ALL METAL SURFACES ARE PLATED, EXCEPT AREA OF CUT

DIMENSION	MILLIMETERS	
	MIN.	MAX.
A	0.90	1.20
A1	0.15	0.35
b	0.34	0.54
D	4.80	5.35
D1	3.90	4.40
D2	0.03	0.23
E	5.70	6.10
E1	5.90	6.42
E2	3.88	4.31
e	1.27	
L	0.45	0.71
M	0.45	0.69

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<b>EUROPEAN PROJECTION</b> 
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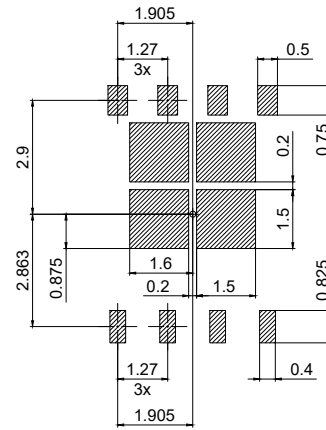
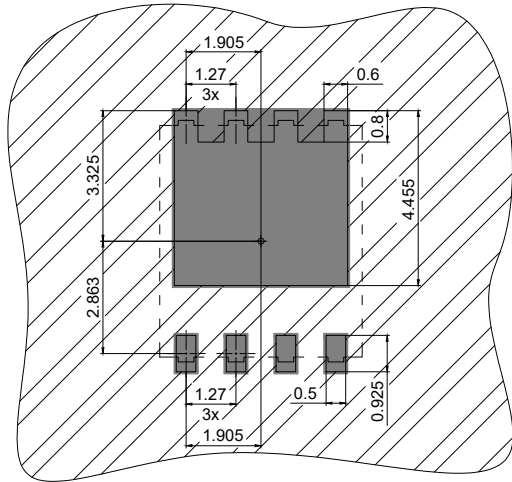
Figure 1 Outline PG-TDSON-8, dimensions in mm



*Dimension in mm*

**Figure 2 Outline Tape (TDSON-8)**

PG-TDSON-8: Recommended Boardpads & Apertures



■ copper

▨ solder mask

▨ stencil apertures

all dimensions in mm

Figure 3 Outline Boardpads (TDSON-8), dimensions in mm

## Revision History

BSC0904NSI

Revision: 2019-11-12, Rev. 2.4

### Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.4	2019-11-12	Update package drawings

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